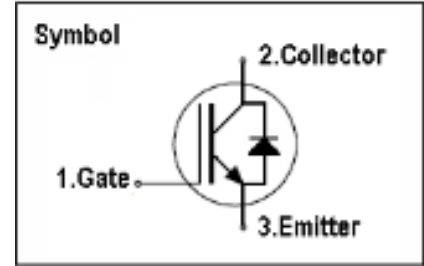


## IGBT

### Features

- 650V,25A
- $V_{CE(sat)(typ.)}=2.1V@V_{GE}=15V,I_C=25A$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA



### General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as Motor control, general inverter and other soft switching applications.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	650	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25^\circ C$ )	50	A
	Continuous Collector Current ( $T_C=100^\circ C$ )	25	A
$I_{CM}$	Pulsed Collector Current (Note 1)	75	A
$I_F$	Diode Continuous Forward Current ( $T_C=100^\circ C$ )	25	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	75	A
$t_{sc}$	Short Circuit Withstand Time	10	us
$P_D$	Maximum Power Dissipation ( $T_C=25^\circ C$ )	69.4	W
	Maximum Power Dissipation ( $T_C=100^\circ C$ )	27.8	W
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th\ j-c}$	Thermal Resistance, Junction to case for IGBT	1.8	$^\circ C/W$
$R_{th\ j-c}$	Thermal Resistance, Junction to case for Diode	3.0	$^\circ C/W$
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	65	$^\circ C/W$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	650	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=650V, V_{GE}=0V$	-	-	100	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=\pm 20V, V_{CE}=0V$	-	-	$\pm 100$	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	5.1	-	6.9	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=25A$	-	2.1	2.7	V
$Q_g$	Total Gate Charge	$V_{CC}=480V$ $V_{GE}=15V$ $I_C=25A$	-	31.2		nC
$Q_{ge}$	Gate-Emitter Charge		-	7.7		nC
$Q_{gc}$	Gate-Collector Charge		-	13.3		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=400V$ $V_{GE}=15V$ $I_C=25A$ $R_G=15\Omega$ Inductive Load $T_C=25^\circ\text{C}$	-	22	-	ns
$t_r$	Turn-on Rise Time		-	44	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	75	-	ns
$t_f$	Turn-off Fall Time		-	88	-	ns
$E_{on}$	Turn-on Switching Loss		-	0.66	-	mJ
$E_{off}$	Turn-off Switching Loss		-	0.49	-	mJ
$E_{ts}$	Total Switching Loss		-	1.15	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=25V$ $V_{GE}=0V$ $f=1\text{MHz}$	-	978	-	pF
$C_{oes}$	Output Capacitance		-	90	-	pF
$C_{res}$	Reverse Transfer Capacitance		-	8	-	pF

**Electrical Characteristics of Diode** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=25A$	-	1.65	3.0	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=400V$ $I_F=25A$ $R_G=15\Omega$	-	60		ns
$I_{rr}$	Diode peak Reverse Recovery Current		-	15.6		A
$Q_{rr}$	Diode Reverse Recovery Charge		-	518		nC

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Performance Characteristics

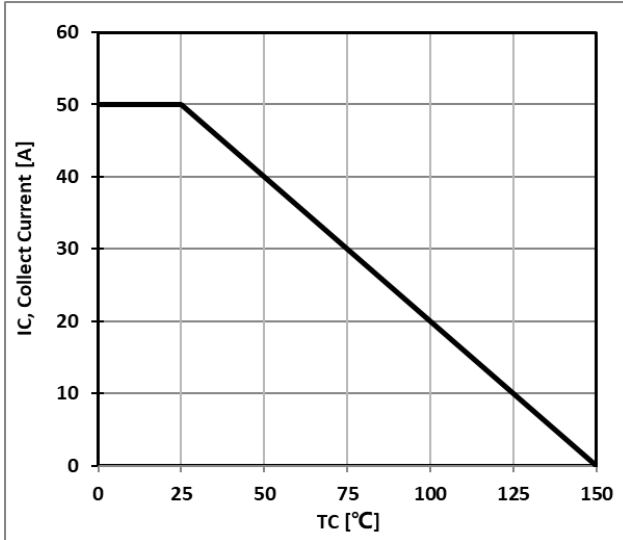


Figure 1: Maximum DC Collector Current VS. case temperature

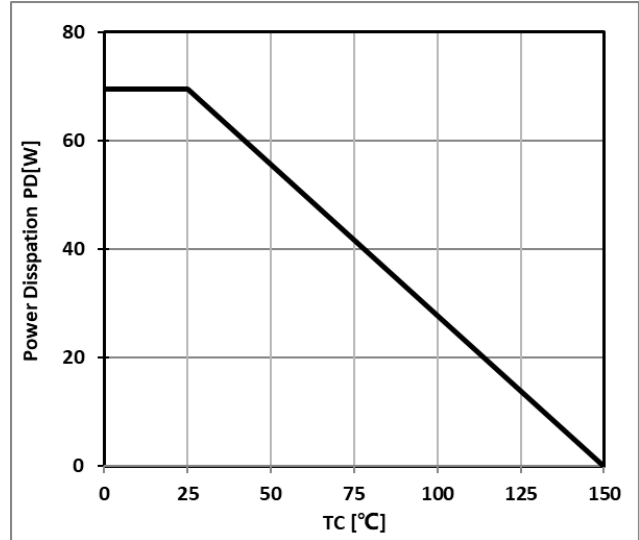


Figure 2: Power Dissipation VS. Case Temperature

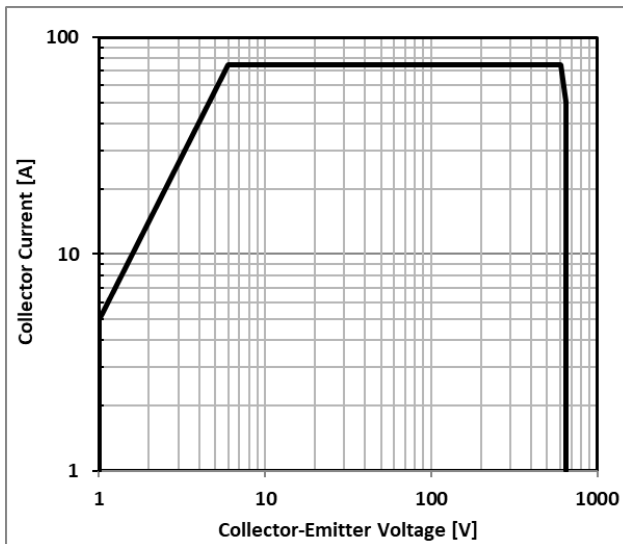


Figure 3: Reverse Bias SOA, TJ=125°C, VGE=15V

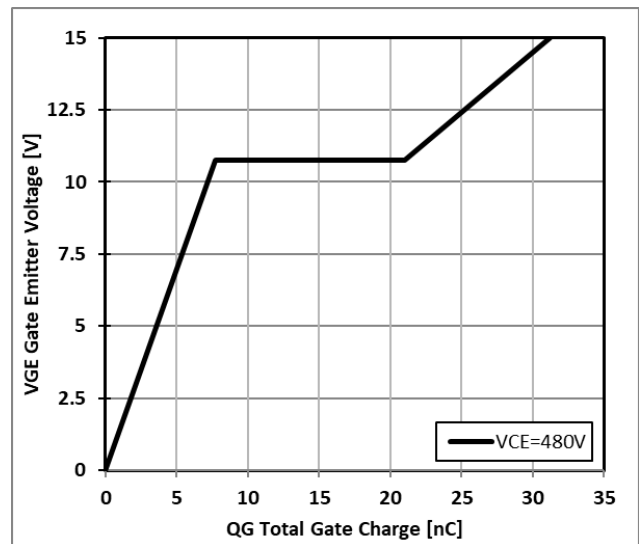


Figure 4: Typical Gate charge VS. VGE, IC=25A

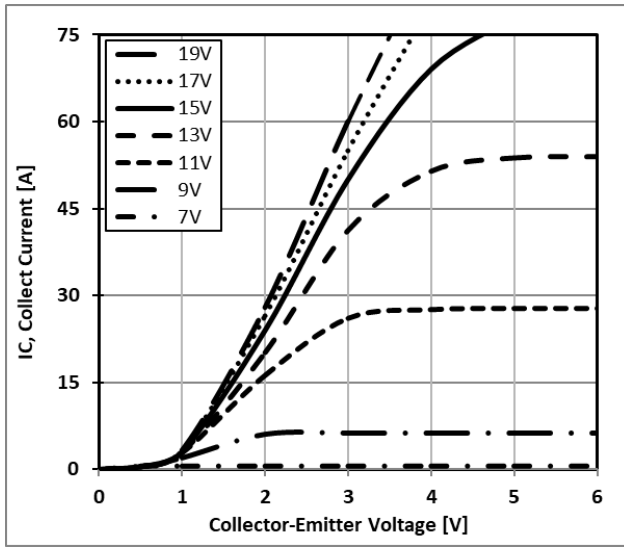


Figure 5: Typical IGBT Output characteristics,  
TC=25°C;tp=300us

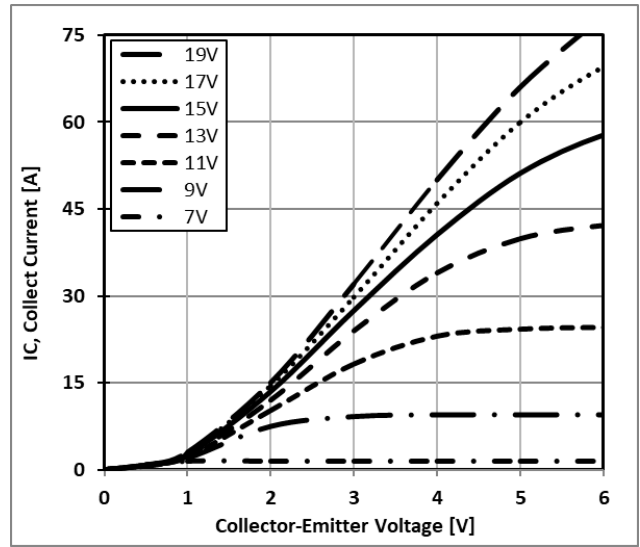


Figure 6: Typical IGBT Output characteristics,  
TC=150°C;tp=300us

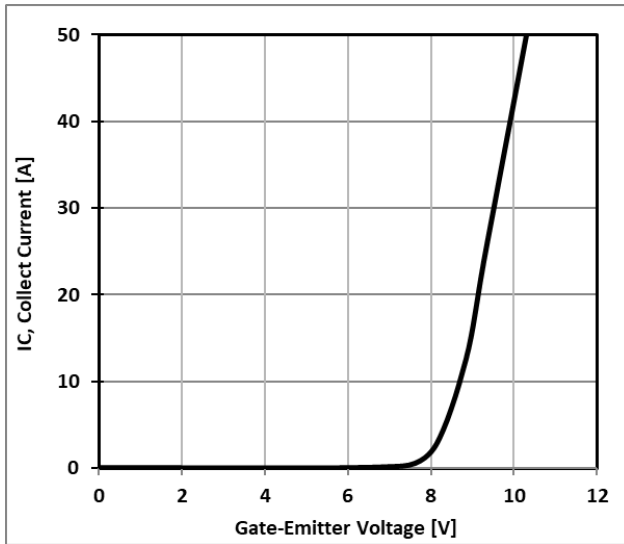


Figure 7: Typical Gate Threshold Voltage

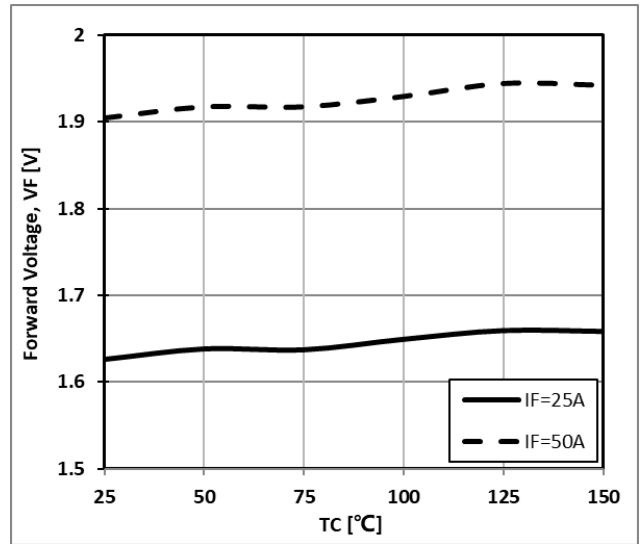


Figure 8: Typical Forward Voltage vs IF

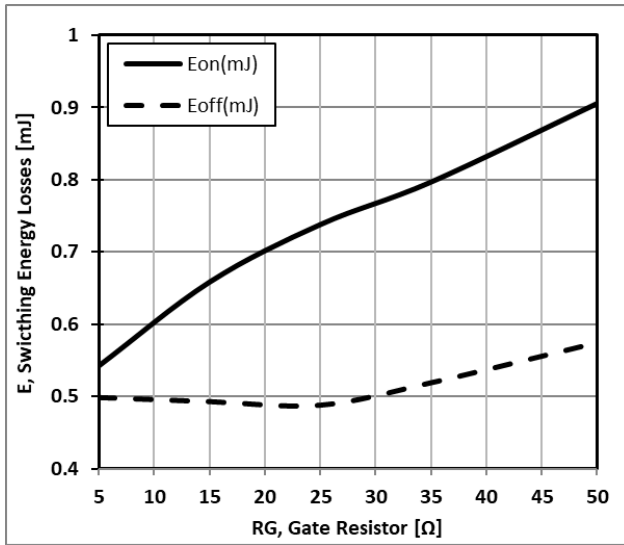


Figure 9: Typical Energy Loss VS. RG, TC=25°C,  
L=200uH, VCE=400V, VGE=15V, IC=25A

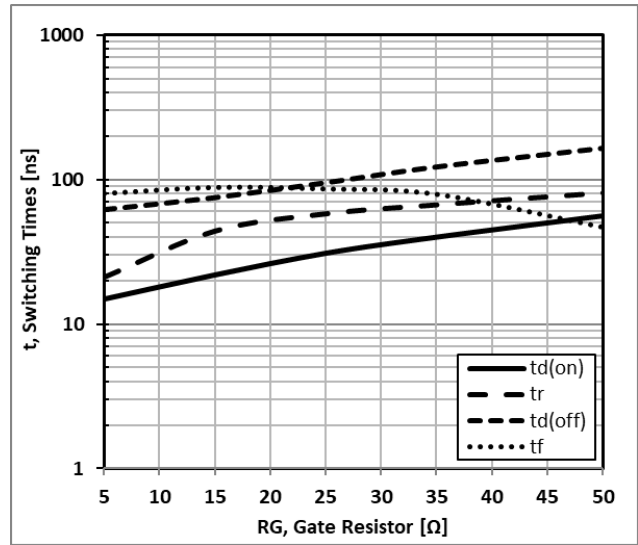


Figure 10: Typical Switching Time VS. RG, TC=25°C,  
L=200uH, VCE=400V, VGE=15V, IC=25A

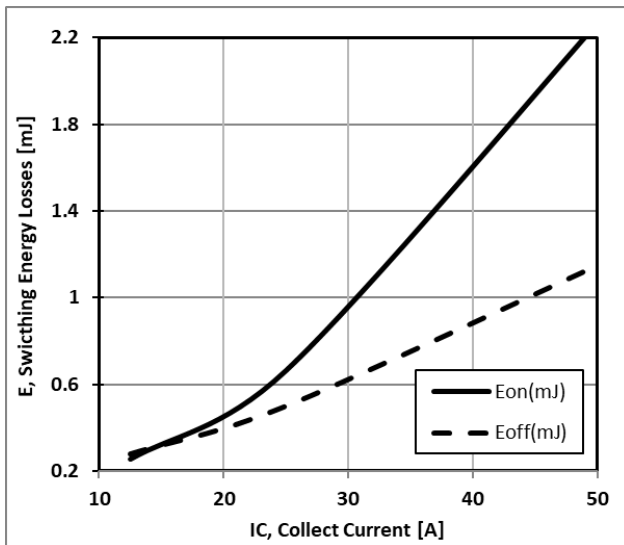


Figure 11: Typical Energy Loss VS. IC, TC=25°C,  
L=200uH, VCE=400V, VGE=15V, RG=15 Ω

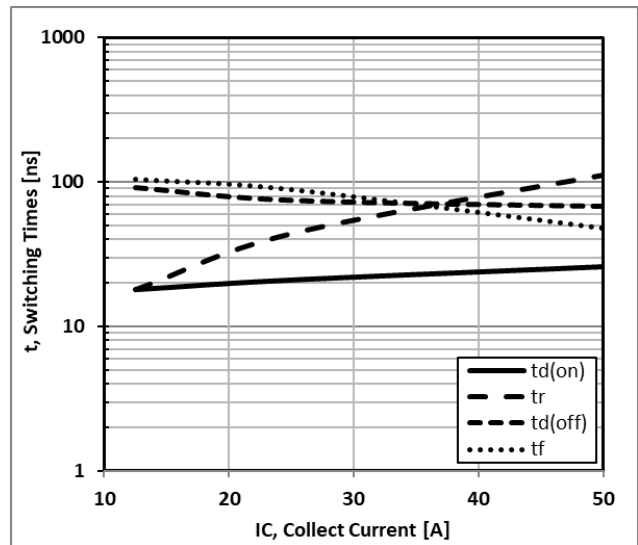


Figure 12: Typical Switching Time VS. IC, TC=25°C,  
L=200uH, VCE=400V, VGE=15V, RG=15 Ω

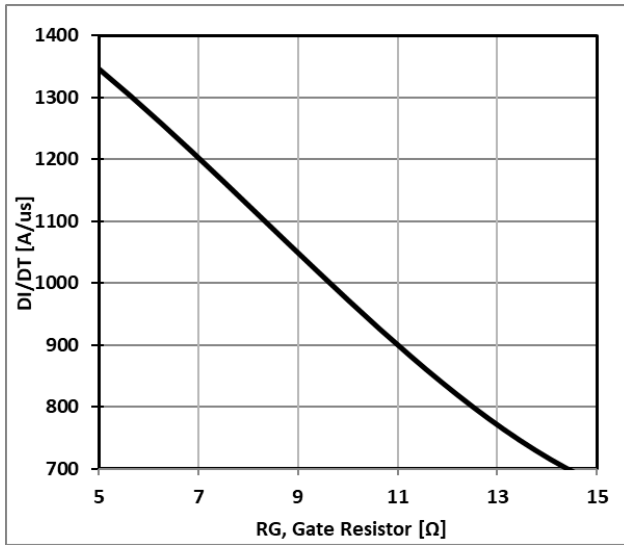


Figure 13: Typical Diode DI/DT VS. RG, TC=25°C  
VCC=400V, VGE=15V, IF=25A

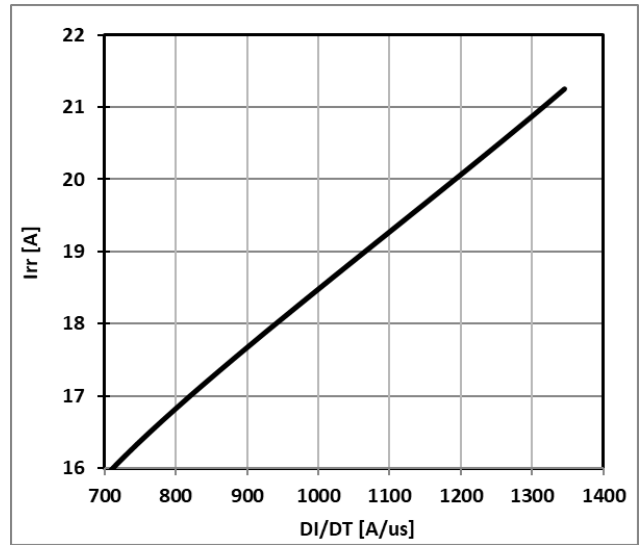


Figure 14: Typical Diode IRR VS. DI/DT, TC=25°C  
VCC=400V, VGE=15V, IF=25A

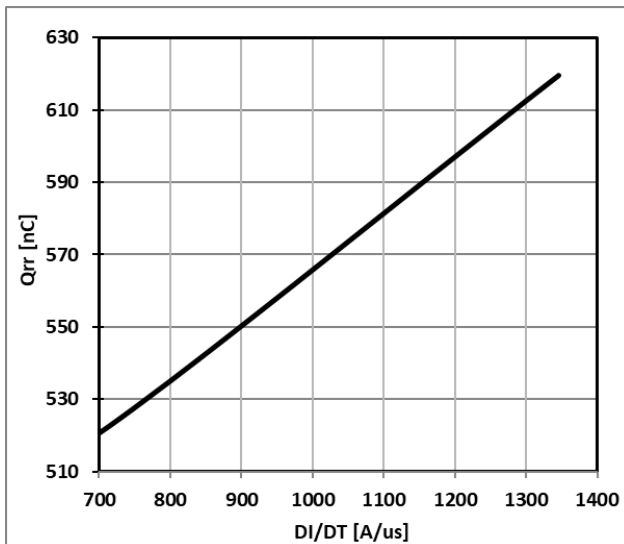


Figure 15: Typical Diode Qrr VS. DI/DT, TC=25°C  
VCC=400V, VGE=15V, IF=25A

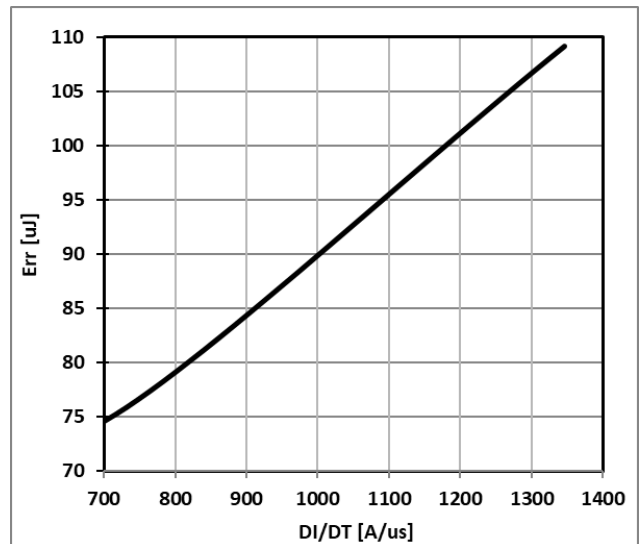


Figure 16: Typical Diode Err VS. DI/DT, TC=25°C  
VCC=400V, VGE=15V, IF=25A

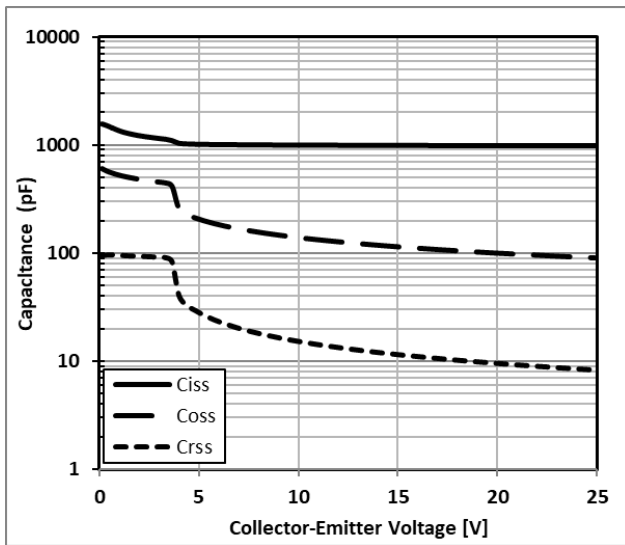


Figure 17: Typical Capacitance VS. VCE,  
VGE=0V,f=1MHz

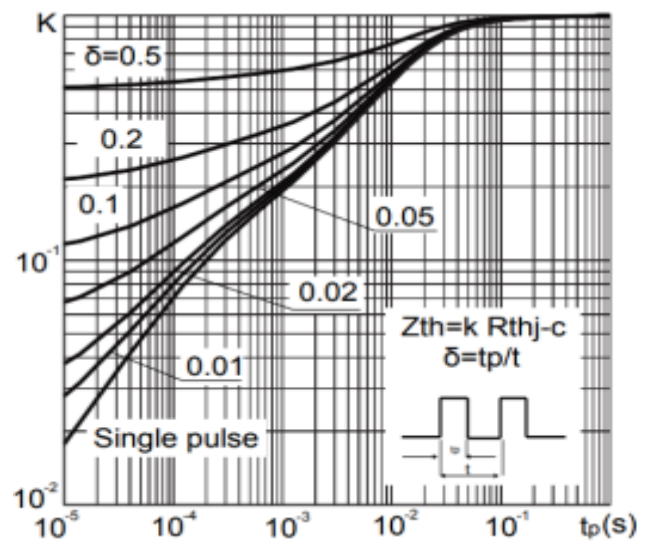
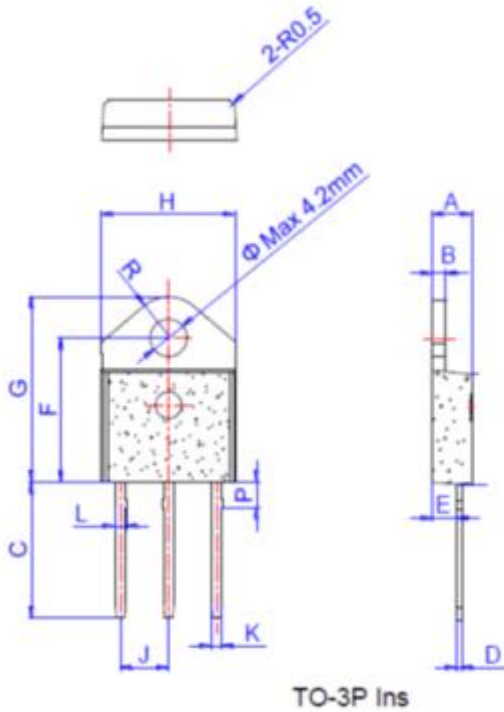


Figure 18: Normalized transient thermal impedance  
junction-to-case

**TO-3P PACKAGE OUTLINE**



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	1.45		1.55	0.057		0.061
C	14.35		15.60	0.565		0.614
D	0.50		0.70	0.020		0.028
E	2.70		2.90	0.106		0.114
F	15.80		16.50	0.622		0.650
G	20.40		21.10	0.803		0.831
H	15.10		15.50	0.594		0.610
J	5.40		5.65	0.213		0.222
K	1.10		1.40	0.043		0.055
L	1.35		1.50	0.053		0.059
P	2.80		3.00	0.110		0.118
R		4.35			0.171	



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